

EPOXY RESIN COMPOSITION FOR SEALING, AND ELECTRONIC COMPONENT
DEVICE

ABSTRACT

5 The present invention provides an epoxy resin composition
for sealing that demonstrates favorable adhesion to a copper
lead frame in which oxidation has progressed and has superior
mold release and continuous moldability. The epoxy resin
composition for sealing includes (A) an epoxy resin, (B) a
10 phenolic resin-based curing agent, (C) an inorganic filler, and
(D) a curing accelerator. The curing accelerator (D) has an
average particle diameter of 10 μm or less, and the ratio of
particles having a particle diameter in excess of 20 μm is 1%
by weight or less. Also, the curing accelerator (D) includes
15 at least one type of curing accelerator selected from the group
consisting of a phosphobetaine compound having a specific
structure; adduct of a phosphine compound having a specific
structure, and quinone compound; and an adduct of a phosphonium
compound having a specific structure, and a silane compound.
20 An electronic component device in which an electronic component
is sealed by a cured product of the aforementioned epoxy resin
composition for sealing is provided.